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## (WO/2006/120733) METHOD FOR PLATING RESIN COMPRISING ADDITIONAL HEAT TREATMENT STEP

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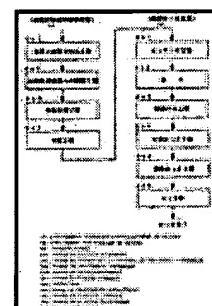
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Title: METHOD FOR PLATING RESIN COMPRISING ADDITIONAL HEAT TREATMENT STEP

Abstract: The addition of a simple step to a process of plating a resin has been found to inhibit a problem that a metal plating film exfoliates together with a thin resin film, due to the rise of a thin film in the surface layer of a resin formed article. A method for plating a resin, wherein a specific region of a resin formed article being estimated to cause the exfoliation of a thin film from a resin surface layer is partially subjected to a high temperature heating treatment, and thereafter, the resin formed article is plated with a metal.



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